

## SSC8L60PN6

#### **N-Channel Enhanced MOSFET**

> Features

VDS	VGS	RDSON Typ.	ID
60V	±20V	1.9mR@10V	160A

#### Description

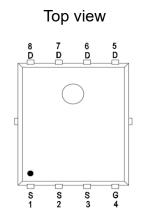
This device is N-Channel enhancement MOSFET. Uses SGT technology and design to provide excellent RDSON with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit. 100% UIS Tested.

- > Applications
- DC/DC converters
- Power supplies
- Motor Drive Control
- Synchronous rectification

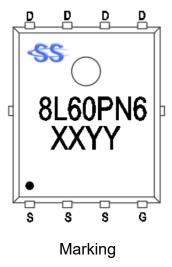
#### > Ordering Information

Device	Package	Shipping
SSC8L60PN6	PDFN5X6	5000/Reel

### > Pin configuration







(XX: product year / YY: product week)

#### > Absolute Maximum Ratings(T<sub>A</sub>=25°C unless otherwise noted)

Symbol	Parameter	Ratings	Unit	
V <sub>DSS</sub>	Drain-to-Source Vol	tage	60	V
V <sub>GSS</sub>	Gate-to-Source Voltage		±20	V
	Questioners Durin Querentd	Tc=25℃	160	•
lo	Continuous Drain Current <sup>d</sup>	Tc=100℃	85	A
	Continuous Drain Current <sup>a</sup>	T <sub>A</sub> =25℃	43	•
IDSM		T <sub>A</sub> =70℃	31	A
I <sub>DM</sub>	Pulsed Drain Curre	ent <sup>b</sup>	640	А
5	Power Dissipation <sup>c</sup>	Tc=25℃	83	14/
PD		Tc=100℃	33	W
5		T <sub>A</sub> =25℃	5.9	14/
Pdsm	Power Dissipation <sup>a</sup>	T <sub>A</sub> =70°C	3.8	W
las	Avalanche Current <sup>b</sup> L=0.5ml	50	А	
Eas	Avalanche Energy <sup>b</sup> L=0.5m	625	mJ	
TJ	Operation junction temp	-55~150		
Tstg	Storage temperature	-55~150	°C	

#### > Thermal Resistance Ratings( $T_A=25^{\circ}$ unless otherwise noted)

Symbol	Parameter	Ratings	Unit
R <sub>θJA</sub>	Junction-to-Ambient Thermal Resistance <sup>a</sup>	21	°C/W
R <sub>θJC</sub>	Junction-to-Case Thermal Resistance	1.5	C/ VV

Note:

- a. The value of R<sub>θJA</sub> is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz.copper, in a still air environment with T<sub>A</sub>=25°C.The value in any given application depends on the user is specific board design. The power dissipation is based on the t ≤ 10s thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation P<sub>D</sub> is based on T<sub>J(MAX)</sub>=150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- d. The maximum current rating is package limited.



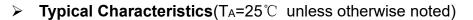
# > Electronics Characteristics(TA=25°C unless otherwise noted)

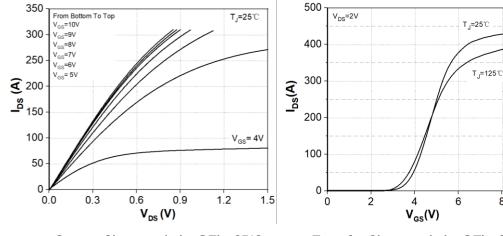
Symbol	Parameter	Test Conditions	Min	Тур.	Max	Unit
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	VGS=0V ,ID=250uA	60			V
$V_{GS \ (th)}$	Gate Threshold Voltage	VDS=VGS ,ID=250uA	1	2	3	V
$R_{DS(on)}$	Drain-Source On- Resistance	VGS=10V , ID=30A		1.9	2.6	mR
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	VDS=48V ,VGS=0V			1	uA
I <sub>GSS</sub>	I <sub>GSS</sub> Gate-Source leak current VGS=±20V ,VDS=0V				±100	nA
G <sub>FS</sub>	Transconductance	VDS=5V ,ID=20A		42		S
$V_{\text{SD}}$	Forward Voltage	VGS=0V , IS=20A		0.8	1.3	V
Rg	Gate Resistance	VDS=0V, f=1MHz		1		R
Ciss	Input Capacitance			5029		
Coss	Output Capacitance	VDS=30V , VGS=0V,		825		pF
Crss	Reverse Transfer Capacitance	f=1MHz		56		р
T <sub>D(ON)</sub>	Turn-on delay time			19		
Tr	Rise time	VGS=10V, RL=2.5R		31		
T <sub>D(OFF)</sub>	Turn-off delay time	VDS=30V , RG=3R		63		ns
Tf	Fall time			23		
Q <sub>G</sub>	Total Gate Charge	VGS=10V, VDS=30V		85		
Q <sub>GS</sub>	Gate Source Charge			19		nC
Q <sub>GD</sub>	Gate Drain Charge	- ID=20A		15		
Trr	Trr Diode Recovery Time IF=20A , di/dt=500			34		ns
Qrr	Diode Recovery Charge	IF=20A , di/dt=500A/us		70		nC



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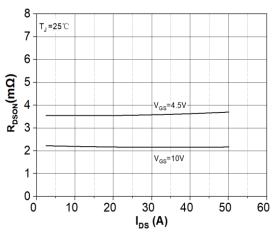
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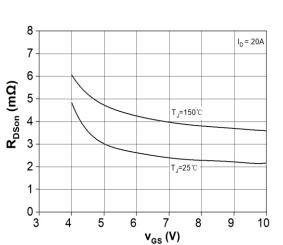


Output Characteristics@Tj= 25℃

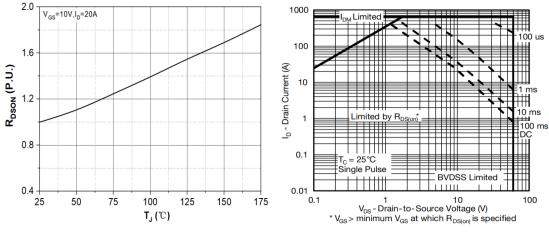




**On-Resistance vs. Drain Current** 



On-Resistance vs. Gate-to-Source Voltage

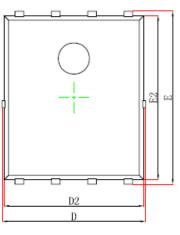


**On-Resistance vs. Junction temperature** 

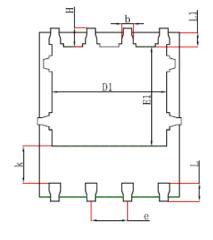
Safe Operating Area



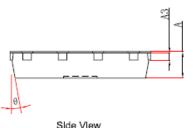
# > Package Information







<u>Bottom Vlew</u> [背视图]



<u>Slde Vlew</u> [側视图]

Package: PDNF5X6-8L
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Symbol	Dimensions	In Millimeters	Dimension	is In Inches	
	Min.	Max.	Min.	Max.	
А	0.900	1.000	0.035	0.039	
A3	0.254	0.254REF		OREF	
D	4.944	5.096	0.195	0.201	
E	5.974	6.126	0.235	0.241	
D1	3.910	4.110	0.154	0.162	
E1	3.375	3.575	0.133	0.141	
D2	4.824	4.976	0.190	0.196	
E2	5.674	5.826	0.223	0.229	
k	1.190	1.390	0.047	0.055	
b	0.350	0.450	0.014	0.018	
е	1.27	1.270TYP		0.050TYP	
L	0.559	0.711	0.022	0.028	
L1	0.424	0.576	0.017	0.023	
Н	0.574	0.726	0.023	0.029	
θ	10°	12°	10°	12°	



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